

CMOS-CCD 1H Delay Line for PAL

Description

The CXL5508M/P are CMOS-CCD delay line ICs that provide 1H delay time for PAL signals, including the external low-pass filter.

Features

- Single 5V power supply
- Low power consumption 60mW (Typ.)
- Built-in peripheral circuits

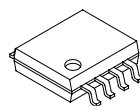
Functions

- 565-bit CCD register
- Clock driver
- Auto-bias circuit
- Input clamp circuit
- Sample-and-hold circuit

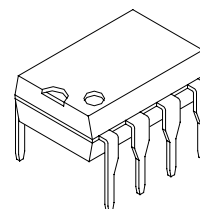
Structure

CMOS-CCD

CXL5508M
8 pin SOP (Plastic)



CXL5508P
8 pin DIP (Plastic)



Absolute Maximum Ratings (Ta = 25°C)

- Supply voltage V_{DD} 6 V
- Operating temperature T_{opr} -10 to +60 °C
- Storage temperature T_{stg} -55 to +150 °C
- Allowable power dissipation

P_D		
CXL5508M	350	mW
CXL5508P	480	mW

Recommended Operating Condition (Ta = 25°C)

- Supply voltage V_{DD} 5 ± 5% V

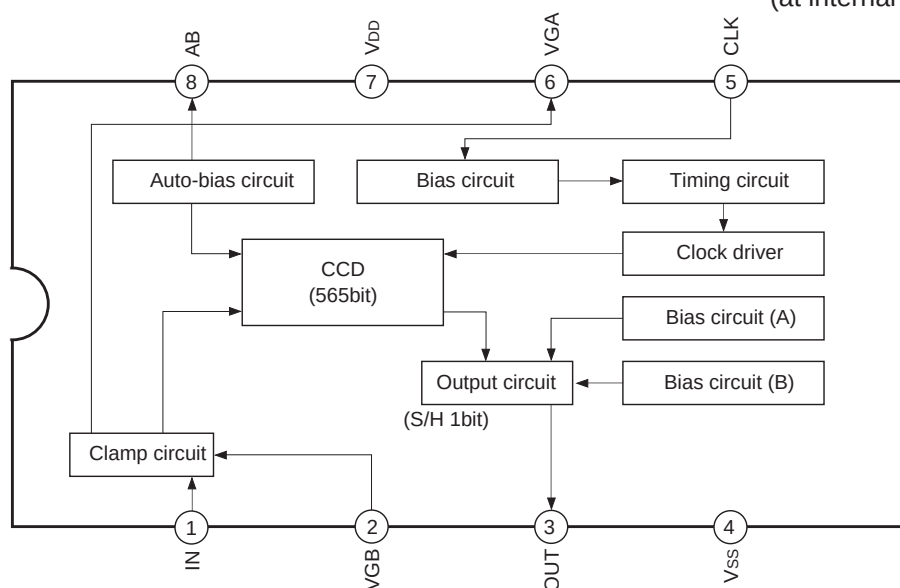
Recommended Clock Conditions (Ta = 25°C)

- Input clock amplitude V_{CLK} 0.3 to 1.0 Vp-p (0.5Vp-p typ.)
- Clock frequency f_{CLK} 8.867238 MHz
- Input clock waveform Sine wave

Input Signal Amplitude

- V_{SIG} 500mVp-p (Typ.), 527mVp-p (Max.) (at internal clamp condition)

Block Diagram and Pin Configuration (Top View)



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Pin Description

Pin No.	Symbol	I/O	Description	Impedance
1	IN	I	Signal input	> 10k Ω at no clamp
2	VGB	I	Gate control B	
3	OUT	O	Signal output	40 to 500 Ω
4	V _{SS}	—	GND	
5	CLK	I	Clock input	> 100k Ω
6	VGA	O	Gate control A	
7	V _{DD}	—	Power supply (5V)	
8	AB	O	Auto-bias DC output	600 to 200k Ω

Description of I/O Signals

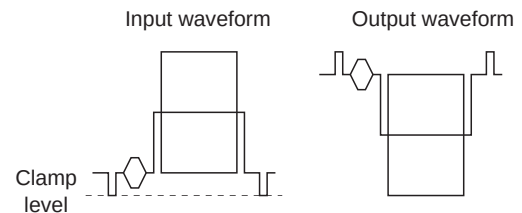
Input signals are low level clamped and output signals are inverted in relation to the input signals. Also, the clamp condition of input signals are controlled by VGB (Pin 2) conditions.

0V Internal clamp condition

5V Non internal clamp condition

Center biased to approx. 2.1V by means of the IC internal resistance (approx. 10k Ω).

In this mode, the input signal is limited to APL 50% and the maximum input signal amplitude is 200mVp-p.



Electrical Characteristics

(Ta = 25°C, V_{DD} = 5V, f_{CLK} = 8.867238MHz, V_{CLK} = 500mVp-p, sine wave)

See "Electrical Characteristics Test Circuit"

Item	Symbol	Test condition	SW condition					Bias condition V1 (V)	Min.	Typ.	Max.	Unit	Note
			1	2	3	4	5						
Supply current	I _{DD}	—	a	a	b	a	—		7	12	17	mA	1
Low frequency gain	GL	200kHz, 500mVp-p, sine wave	a	a	b	a	b		−2	0	2	dB	2
Frequency response	fg	200kHz ↔ 2MHz, 150mVp-p, sine wave	b c	a	a	b	b	2.1	−1.8	−1.8	0	dB	3
S/H pulse coupling	CP	No signal input	—	b	a	b	a	2.1	—	—	350	mVp-p	4
S/N ratio	SN	No signal input	—	b	a	b	c		54	56	—	dB	5
Linearity	LIS	5-staircase wave (For luminance signals only)	b	a	b	a	a	—	37	40	43	%	6
	LIL		b	a	b	a	a		18	20	22		
	LIC		b	a	b	a	a		56	60	64		

Notes

(1) This is the IC supply current value during clock and signal input.

(2) GL is the output gain of OUT pin when a 500mVp-p, 200kHz sine wave is fed to IN pin.

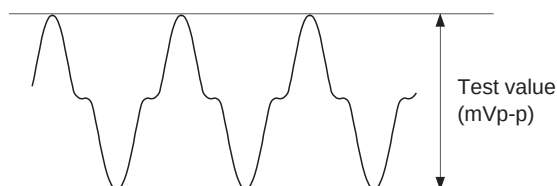
$$GL = 20 \log \frac{\text{OUT pin output voltage [mVp-p]}}{500 [\text{mVp-p}]} [\text{dB}]$$

(3) Indicates the dissipation at 2MHz in relation to 200kHz.

From the output voltage at OUT pin when a 150mVp-p, 200kHz sine wave is fed to IN pin, and from the output voltage at OUT pin when a 150mVp-p, 2MHz sine wave is fed to same, calculation is made according to the following formula. Input bias is tested at 2.1V.

$$fg = 20 \log \frac{\text{OUT pin output voltage (2MHz) [mVp-p]}}{\text{OUT pin output voltage (200kHz) [mVp-p]}} [\text{dB}]$$

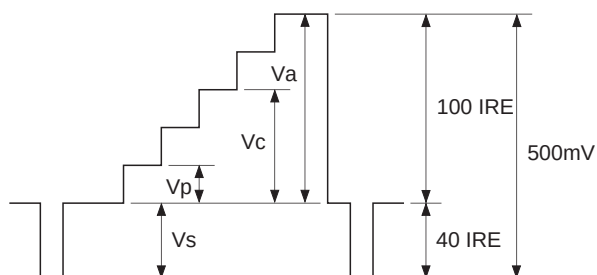
(4) The internal clock component to the output signal during no-signal input and the leakage of that high harmonic component are tested. Input bias is tested at 2.1V.



(5) Input no signal noise components are tested with the video noise meter at BPF 10kHz to 3MHz. This is calculated from the output gain (GL), at the input of 200kHz, 500mVp-p and according to the following formula.

$$S/N = -20 \cdot \log \frac{\text{Noise (mVrms)}}{0.5 \cdot 10^{GL/20}} [\text{dB}]$$

(6) Respective outputs are tested at the input of the 5-staircase waves seen in the figure below (luminance signals only) and calculated according to the formula below.
(However, output signals become inverted with regards to input.)



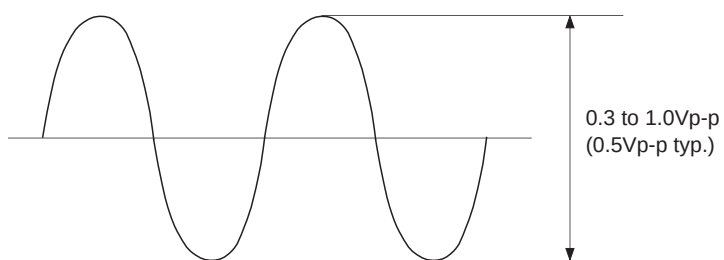
$$LIS = \frac{Vs}{Va} \times 100 [\%]$$

$$LIL = \frac{Vp}{Va} \times 100 [\%]$$

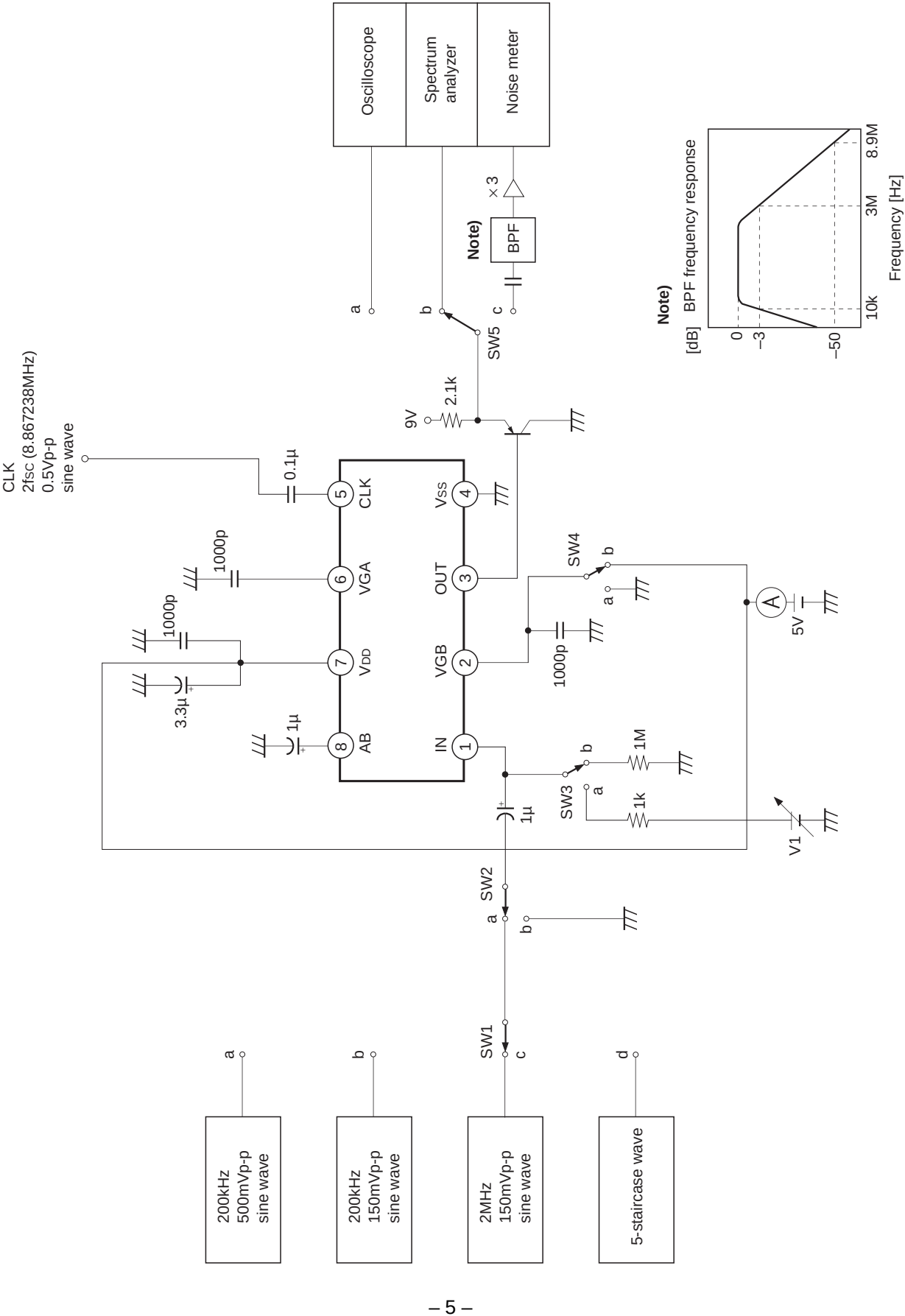
$$LIC = \frac{Vc}{Va} \times 100 [\%]$$

Clock

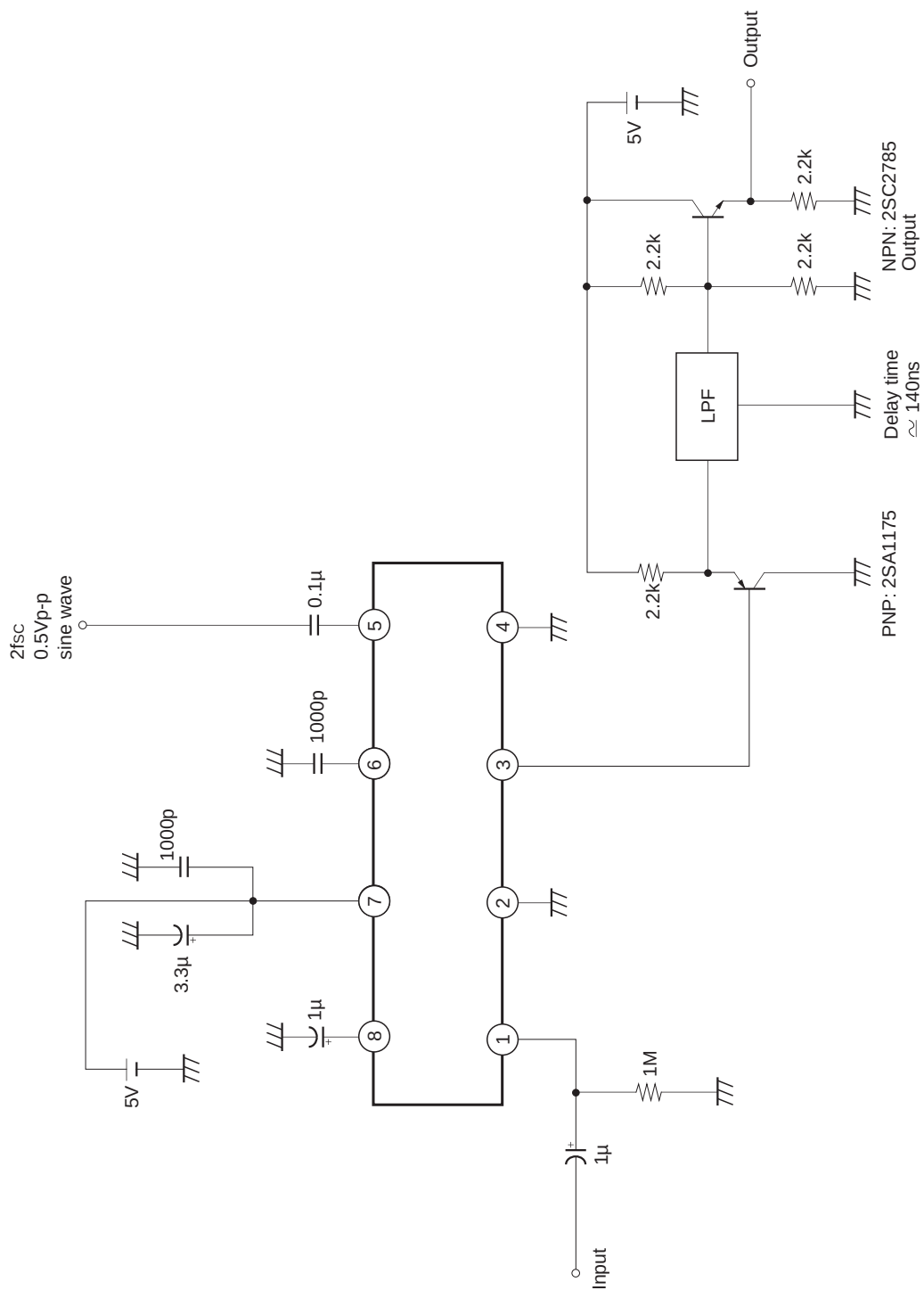
2fsc (8.867238MHz) sine wave



Electrical Characteristics Test Circuit

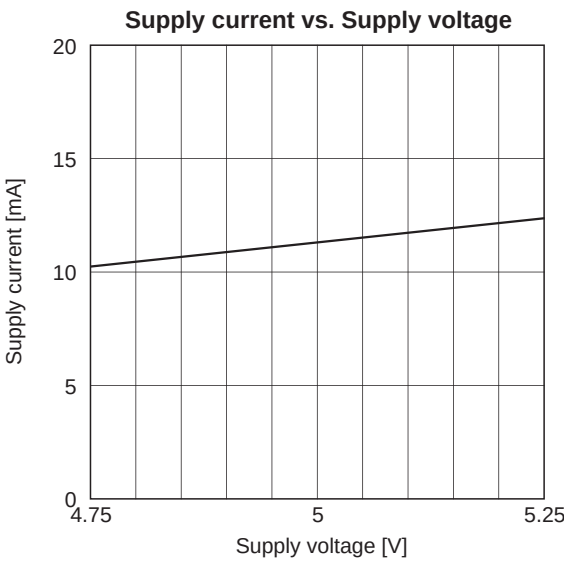
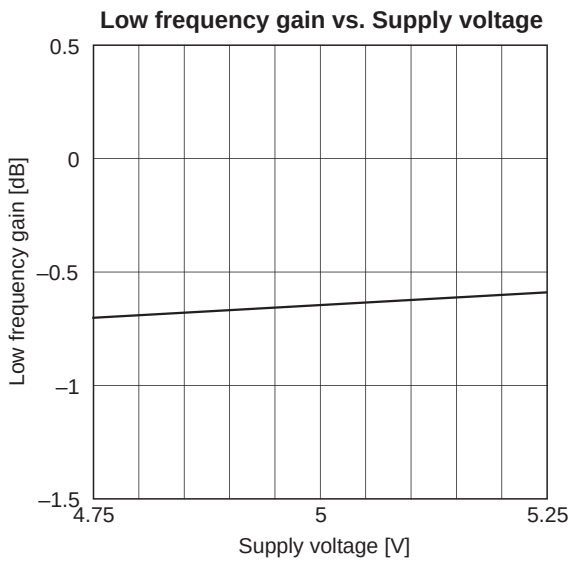
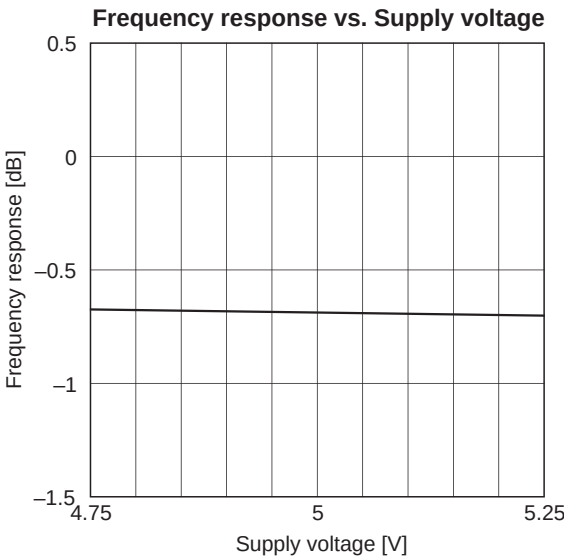
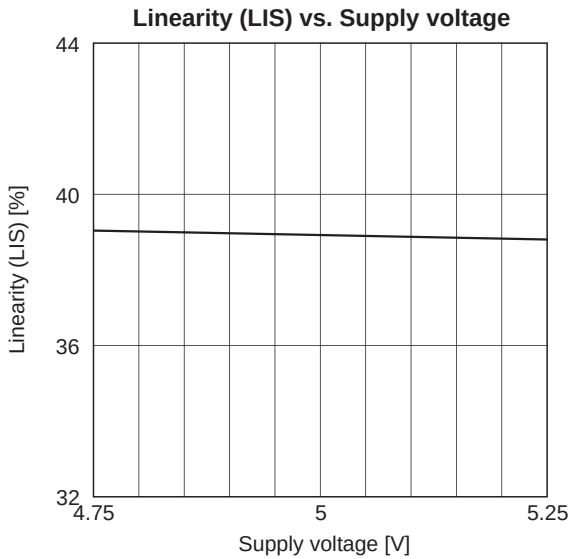
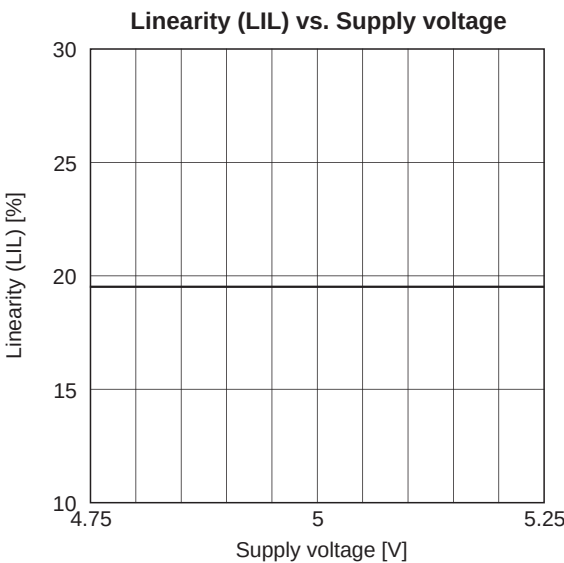
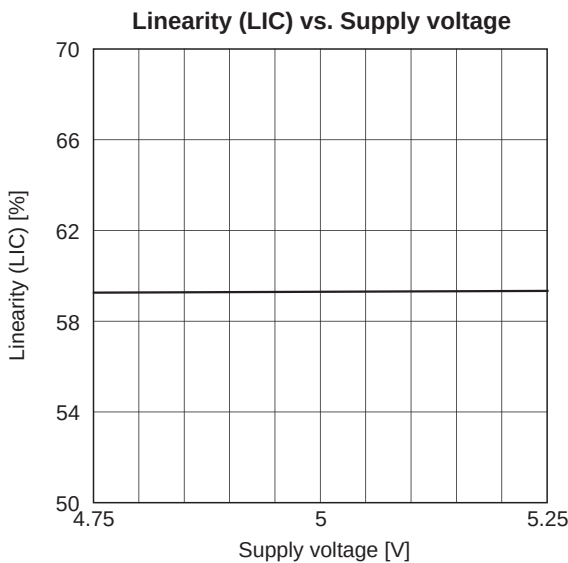


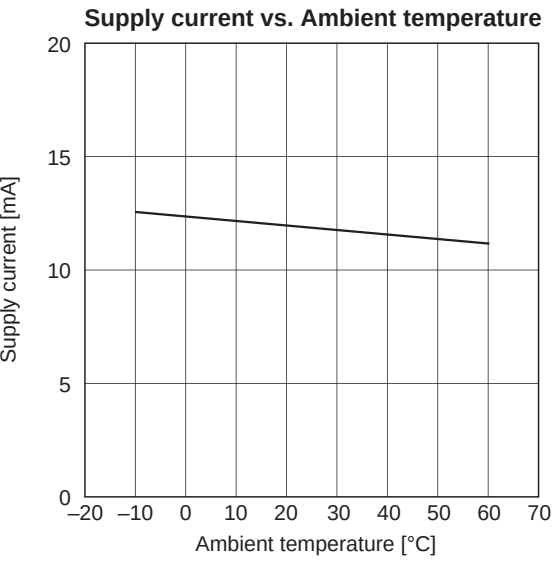
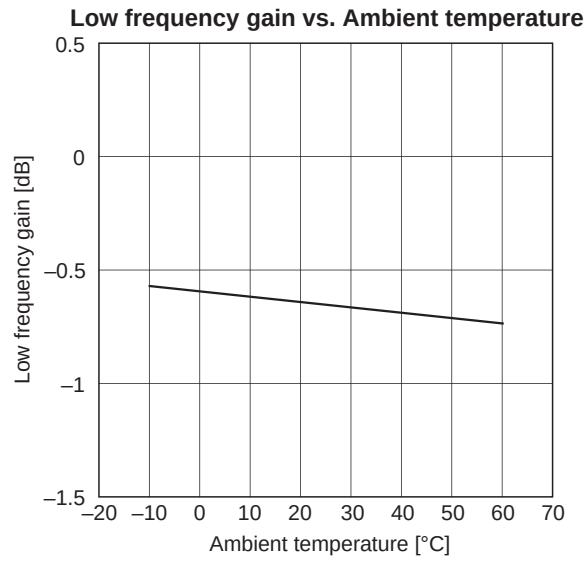
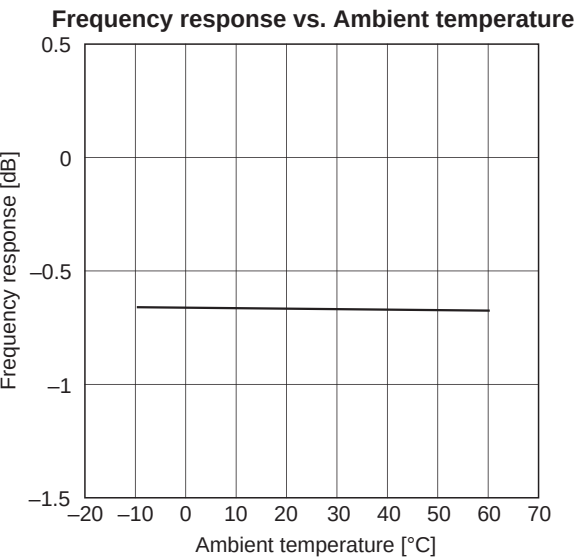
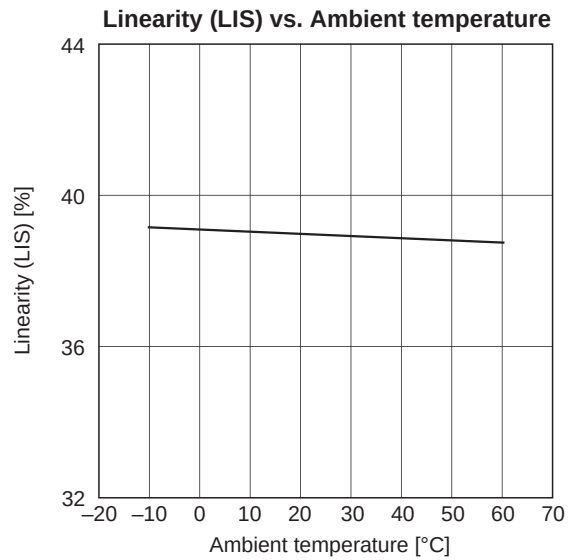
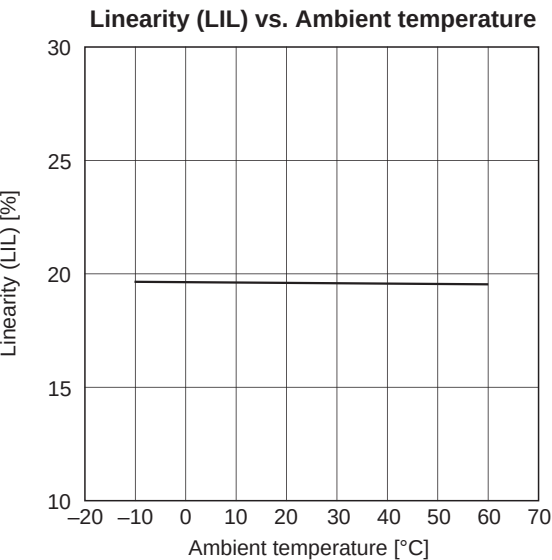
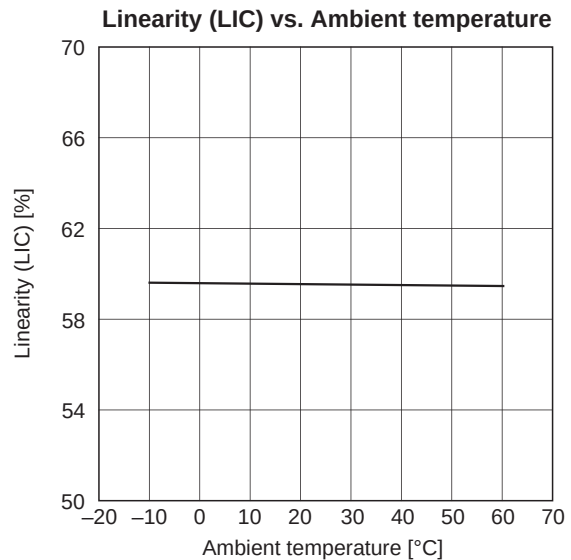
Application Circuit



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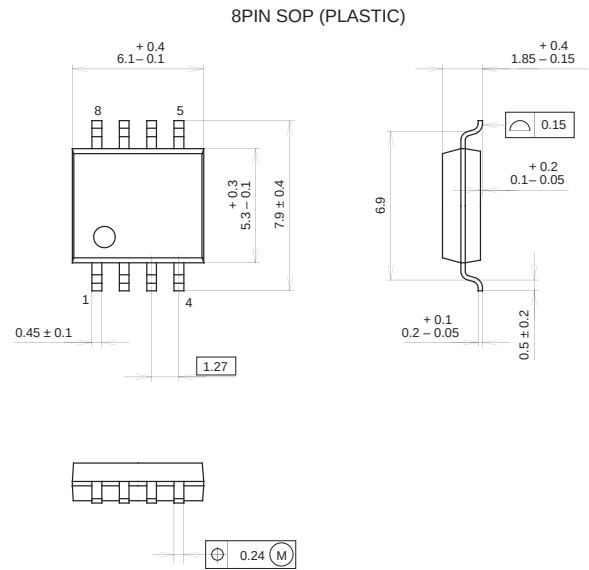
Example of Representative Characteristics





Package Outline Unit: mm

CXL5508M

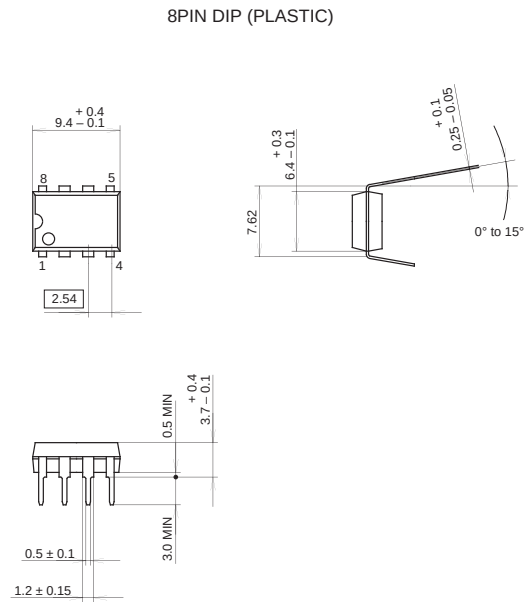


PACKAGE STRUCTURE

SONY CODE	SOP-8P-L01
EIAJ CODE	SOP008-P-0300
JEDEC CODE	

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.1g

CXL5508P



PACKAGE STRUCTURE

SONY CODE	DIP-8P-01
EIAJ CODE	DIP008-P-0300
JEDEC CODE	

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.5g